

N-Channel Super-junction MOSFET Gen III

MOSFET

Metal Oxide Semiconductor Field Effect Transistor

650V Super-junction Gen III

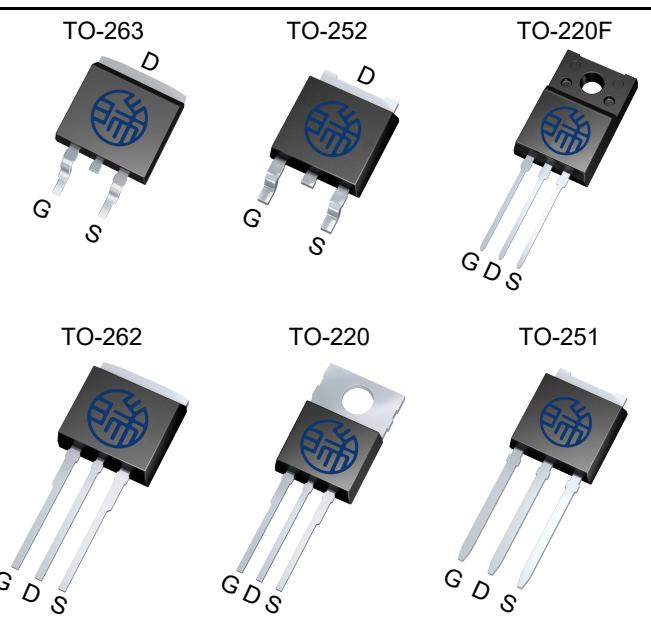
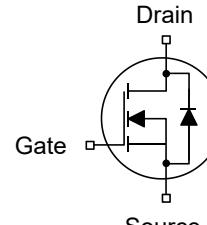
650V Super-junction Gen III Power Transistor

HRD65T230x Data Sheet

Rev. 2020 V1.0



650V Super-junction Power MOSFET Gen III

<p>Description</p> <p>650V Super-junction MOSFET Gen III</p> <p>Super-junction MOSFET Gen III is designed by HR-Micro Semiconductor Company, according to the SJ principle. This device provide an excellent Gate charge and $R_{DS(on)}$, which leads to extremely low communication and conduction losses. So it is very suitable for AC/DC power conversion, Laptop adapter, Lighting, and industrial power applications.</p>																									
<p>Features</p> <ul style="list-style-type: none"> Very low FOM $R_{DS(on)} \times Q_g$ 100% avalanche tested Easy to use/drive RoHS compliant 																									
<p>Applications</p> <ul style="list-style-type: none"> Switch Mode Power Supply (SMPS) Uninterruptible Power Supply (UPS) Power Factor Correction (PFC) Charger 	 																								
<p>Key Performance Parameters</p> <table border="1"> <thead> <tr> <th>Parameter</th><th>Value</th><th>Unit</th></tr> </thead> <tbody> <tr> <td>$V_{DS} @ T_{j,max}$</td><td>700</td><td>V</td></tr> <tr> <td>$R_{DS(on),max}$</td><td>0.23</td><td>Ω</td></tr> <tr> <td>$Q_{g,typ}$</td><td>26.1</td><td>nC</td></tr> <tr> <td>I_D</td><td>15</td><td>A</td></tr> <tr> <td>$I_{D,pulse}$</td><td>45</td><td>A</td></tr> <tr> <td>$E_{OSS} @ 400V$</td><td>3.36</td><td>μJ</td></tr> <tr> <td>Body Diode dI_F/dt</td><td>500</td><td>$A/\mu s$</td></tr> </tbody> </table>	Parameter	Value	Unit	$V_{DS} @ T_{j,max}$	700	V	$R_{DS(on),max}$	0.23	Ω	$Q_{g,typ}$	26.1	nC	I_D	15	A	$I_{D,pulse}$	45	A	$E_{OSS} @ 400V$	3.36	μJ	Body Diode dI_F/dt	500	$A/\mu s$	
Parameter	Value	Unit																							
$V_{DS} @ T_{j,max}$	700	V																							
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<p>Device Marking and Package Information</p> <table border="1"> <thead> <tr> <th>Device</th><th>Package</th><th>Marking</th></tr> </thead> <tbody> <tr> <td>HRD65T230B</td><td>TO-263</td><td>D65T230B</td></tr> <tr> <td>HRD65T230D</td><td>TO-252</td><td>D65T230D</td></tr> <tr> <td>HRD65T230F</td><td>TO-220F</td><td>D65T230F</td></tr> <tr> <td>HRD65T230L</td><td>TO-262</td><td>D65T230L</td></tr> <tr> <td>HRD65T230P</td><td>TO-220</td><td>D65T230P</td></tr> <tr> <td>HRD65T230U</td><td>TO-251</td><td>D65T230U</td></tr> </tbody> </table>	Device	Package	Marking	HRD65T230B	TO-263	D65T230B	HRD65T230D	TO-252	D65T230D	HRD65T230F	TO-220F	D65T230F	HRD65T230L	TO-262	D65T230L	HRD65T230P	TO-220	D65T230P	HRD65T230U	TO-251	D65T230U				
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HRD65T230P	TO-220	D65T230P																							
HRD65T230U	TO-251	D65T230U																							

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage($V_{GS}=0\text{V}$)	V_{DS}	650	V
Continuous Drain Current ¹⁾	I_D	15	A
$T_C = 100^\circ\text{C}$		9	
Pulsed Drain Current ²⁾	$I_{D,\text{pulse}}$	45	A
Gate-Source Voltage	V_{GS}	± 30	V
Single Pulse Avalanche Energy	E_{AS}	304	mJ
Repetitive Avalanche Energy	E_{AR}	1.6	mJ
Avalanche Current	I_{AR}	3	A
MOSFET dv/dt Ruggedness, $V_{DS} = 0 \dots 480\text{V}$	dv/dt	50	V/ns
Power Dissipation For TO-263、TO-252、TO-262、TO-220、TO-251	P_D	83	W
Power Dissipation For TO-220F		28	
Continuous Diode Forward Current	I_S	12.8	A
Diode Pulsed Current ²⁾	$I_{S,\text{pulse}}$	45	
Reverse Diode dv/dt ³⁾	dv/dt	15	V/ns
Maximum Diode Commutation Speed	di _F /dt	500	A/ μs
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55~+150	°C

Thermal Resistance For TO-263、TO-252、TO-262、TO-220、TO-251

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R_{thJC}	1.5	°C/W
Thermal Resistance, Junction-to-Ambient	R_{thJA}	62	

Thermal Resistance For TO-220F

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R_{thJC}	4.4	°C/W
Thermal Resistance, Junction-to-Ambient	R_{thJA}	80	

Notes

- 1) Limited by maximum junction temperature.
- 2) Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3) Identical low side and high side switch with identical R_G .

Electrical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	650	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 650V$ $V_{GS} = 0V, T_J = 25^\circ\text{C}$	--	--	1	μA
		$V_{DS} = 650V,$ $V_{GS} = 0V, T_J = 150^\circ\text{C}$	--	--	100	
Gate-Source Leakage Current	I_{GSS}	$V_{GS} = \pm 30V$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	3.0	3.5	4.0	V
Drain-Source On-State-Resistance	$R_{DS(\text{on})}$	$V_{GS} = 10V, I_D = 7.5\text{A}$	--	0.205	0.23	Ω
Gate Resistance	R_G	$f = 1.0\text{MHz}$ open drain	--	3.0	--	Ω
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 100V$ $f = 1.0\text{MHz}$	--	1010	--	pF
Output Capacitance	C_{oss}		--	46.9	--	
Reverse Transfer Capacitance	C_{rss}		--	2.1	--	
Total Gate Charge	Q_g	$V_{DD} = 520V, I_D = 15\text{A}$ $V_{GS} = 10V$	--	26.1	--	nC
Gate-Source Charge	Q_{gs}		--	8.7	--	
Gate-Drain Charge	Q_{gd}		--	10.1	--	
Gate Plateau Voltage	$V_{Plateau}$		--	6.59	--	V
Turn-on Delay Time	$t_{d(\text{on})}$	$V_{DD} = 400V, I_D = 15\text{A}$ $R_G = 15\Omega, V_{GS} = 10V$	--	14	--	ns
Turn-on Rise Time	t_r		--	8	--	
Turn-off Delay Time	$t_{d(\text{off})}$		--	55	--	
Turn-off Fall Time	t_f		--	7	--	
Drain-Source Body Diode Characteristics						
Body Diode Forward Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{SD} = 7.5\text{A},$ $V_{GS} = 0V$	--	0.9	1.2	V
Reverse Recovery Time	t_{rr}	$V_R = 400V$ $I_F = 7.5\text{A}, di_F/dt = 100\text{A}/\mu\text{s}$	--	240	--	ns
Reverse Recovery Charge	Q_{rr}		--	2	--	μC
Peak Reverse Recovery Current	I_{rrm}		--	17	--	A

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

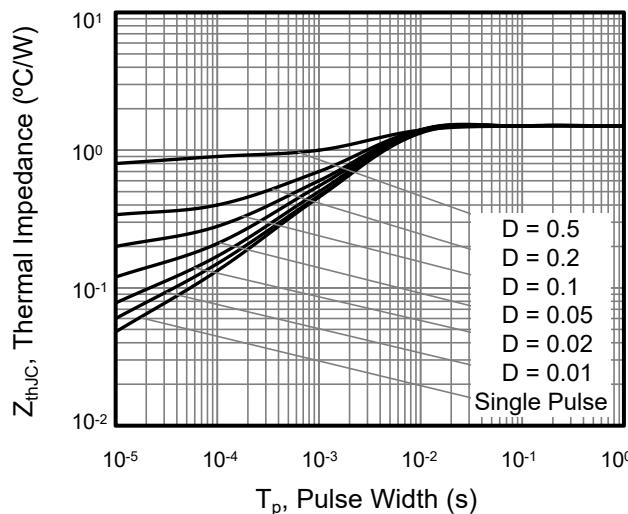


Figure 1. Transient Thermal Impedance
For TO-263/TO-252/TO-262/TO-220/TO-251

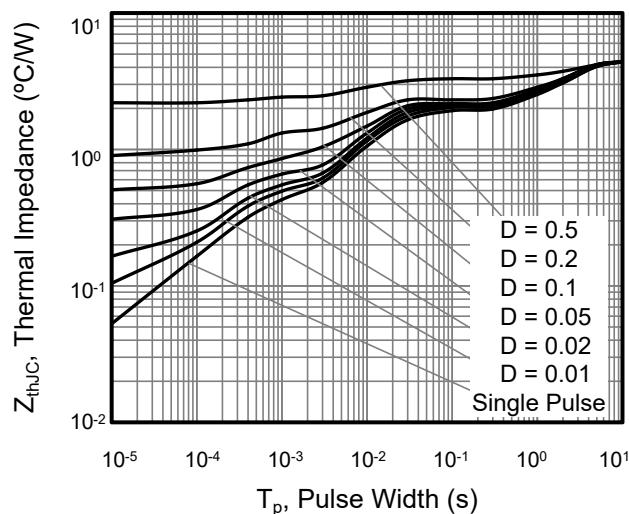


Figure 2. Transient Thermal Impedance
For TO-220F

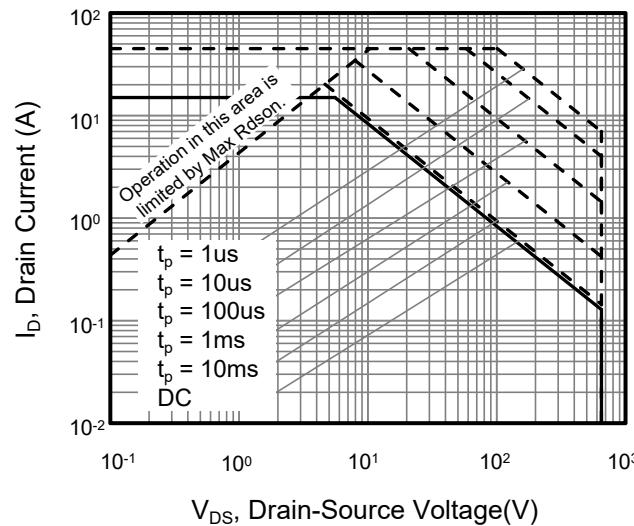


Figure 3. Safe Operation Area
For TO-263/TO-252/TO-262/TO-220/TO-251

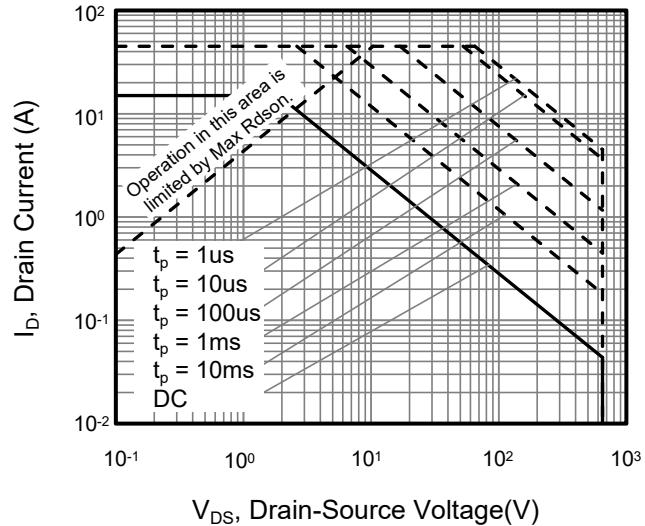


Figure 4. Safe Operation Area
For TO-220F

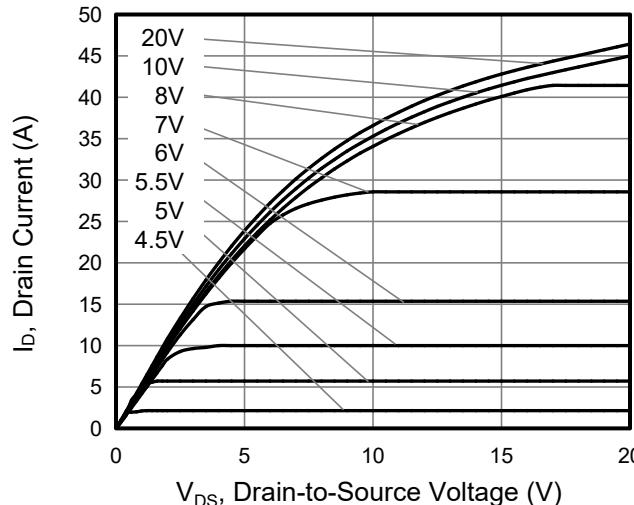


Figure 5. Output Characteristics

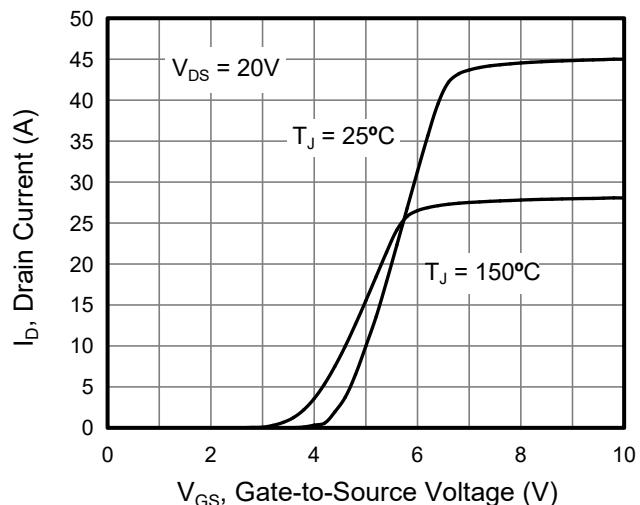


Figure 6. Transfer Characteristics

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

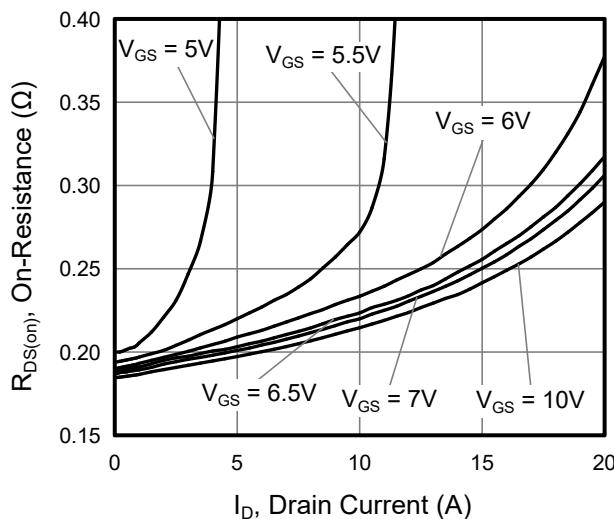


Figure 7. On-Resistance vs Drain Current

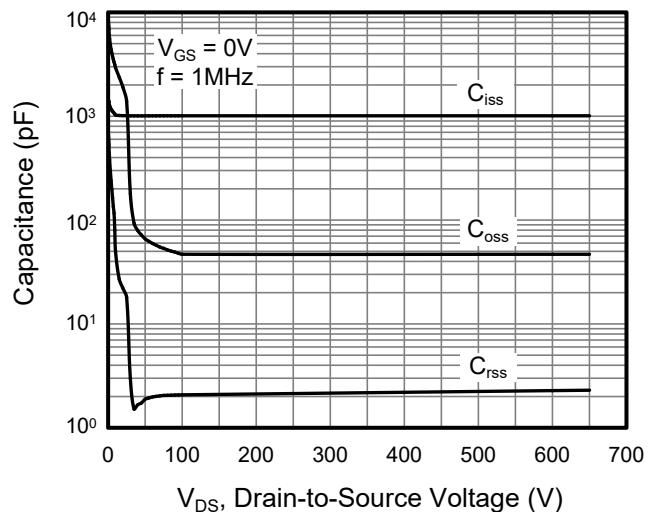


Figure 8. Capacitance

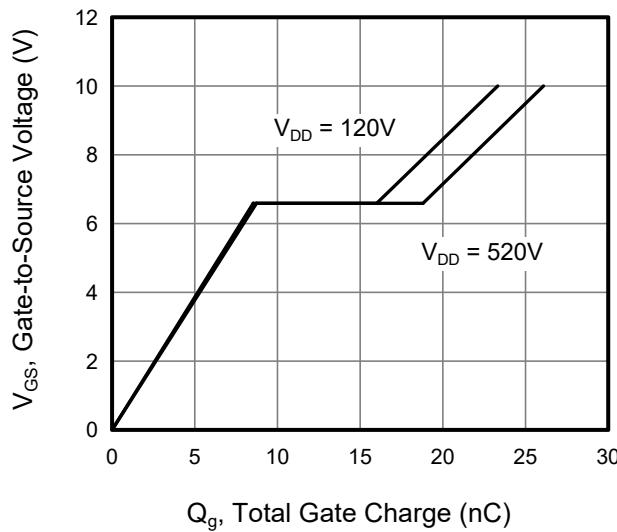


Figure 9. Gate Charge

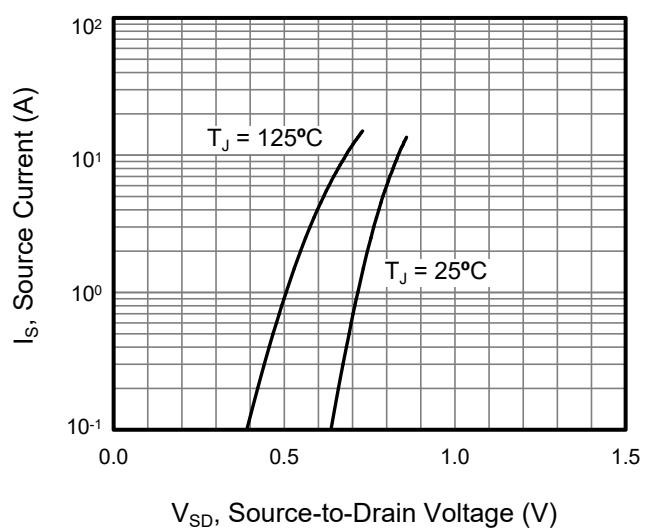


Figure 10. Body Diode Forward Voltage

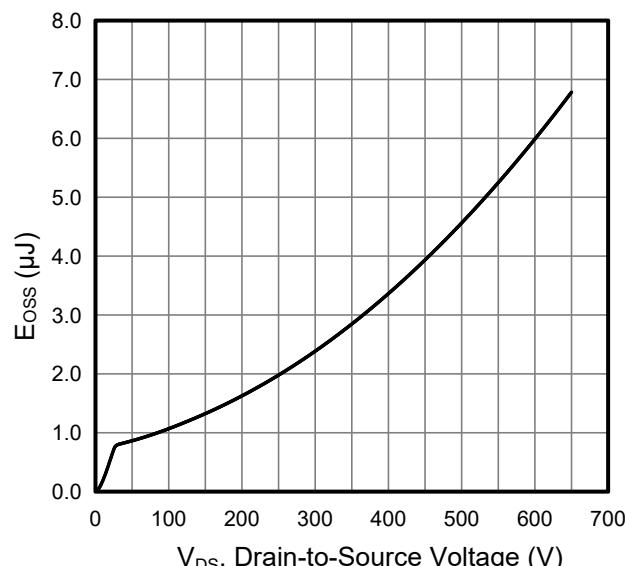


Figure 11. Typ. Coss Stored Energy

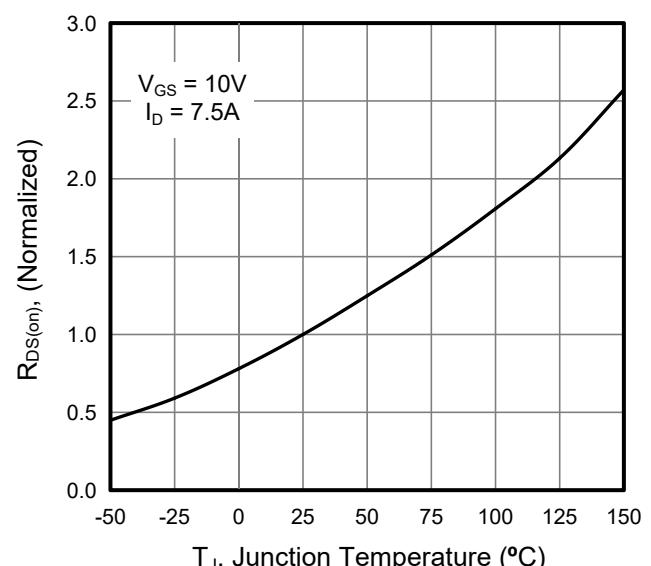
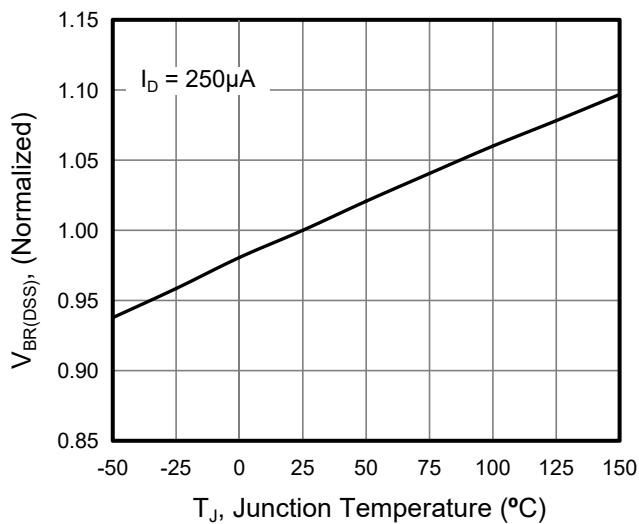


Figure 12. On-Resistance vs Temperature

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted



**Figure 13. Breakdown Voltage vs
Junction Temperature**

Figure A: Gate Charge Test Circuit and Waveform

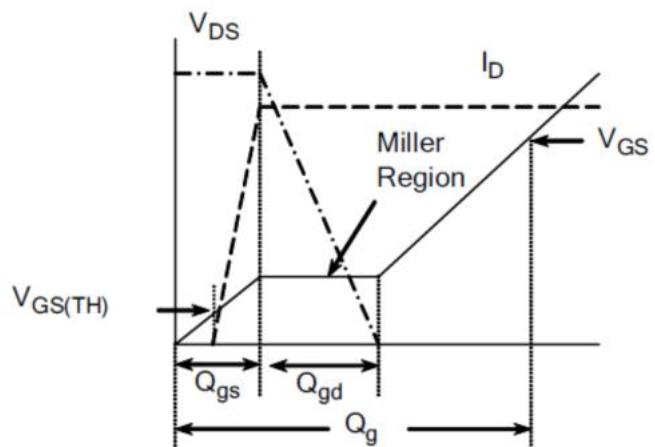
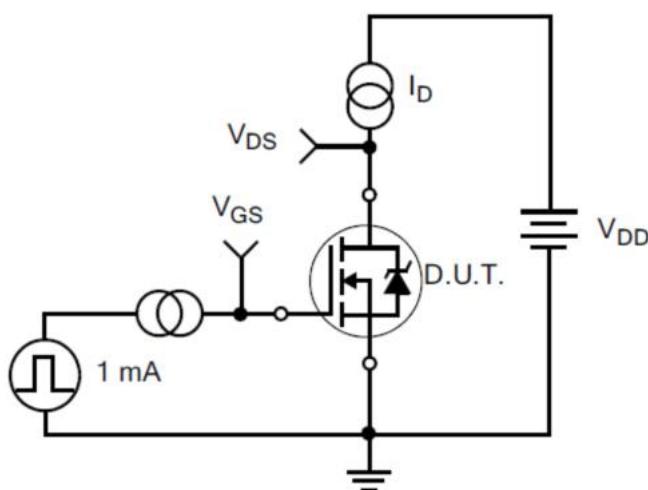


Figure B: Resistive Switching Test Circuit and Waveform

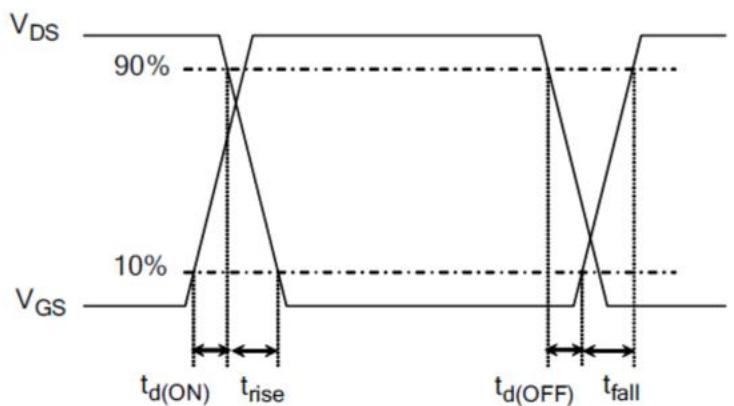
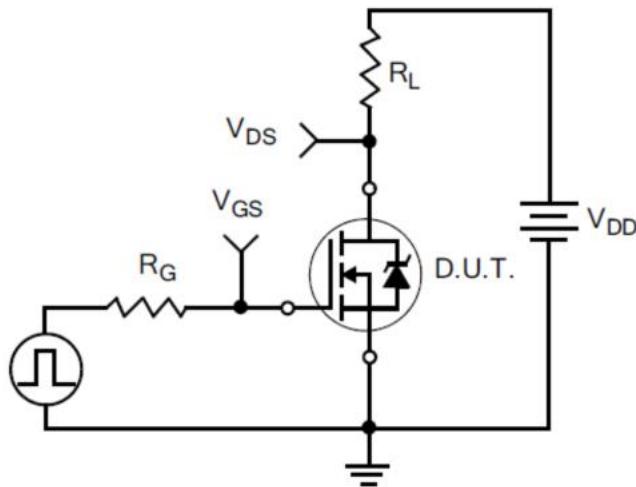
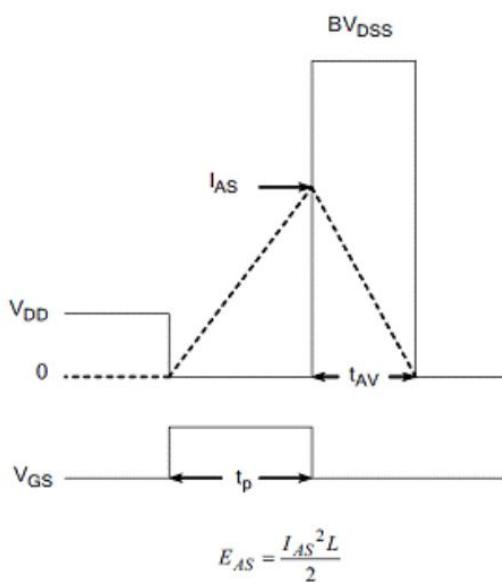
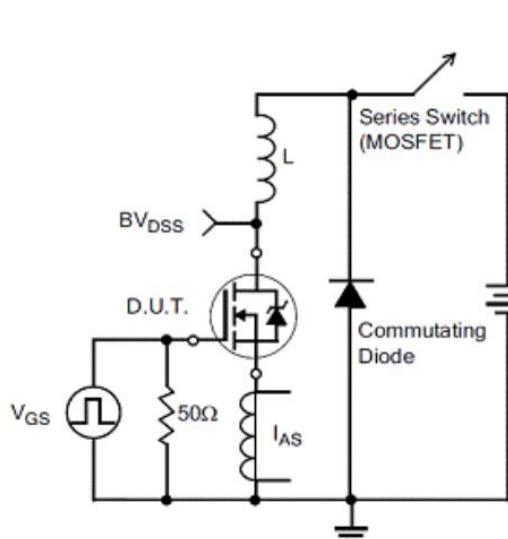
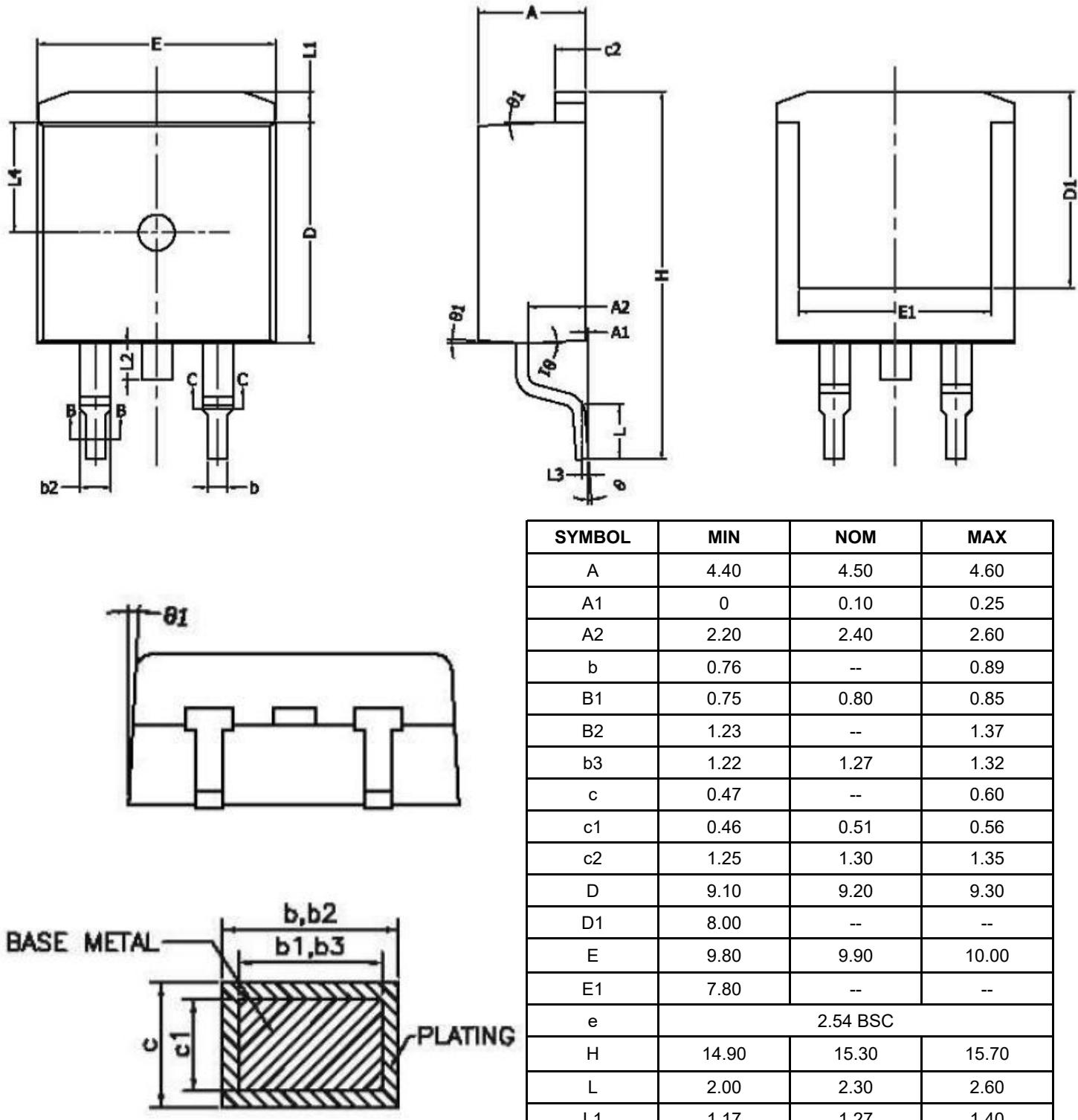


Figure C: Unclamped Inductive Switching Test Circuit and Waveform

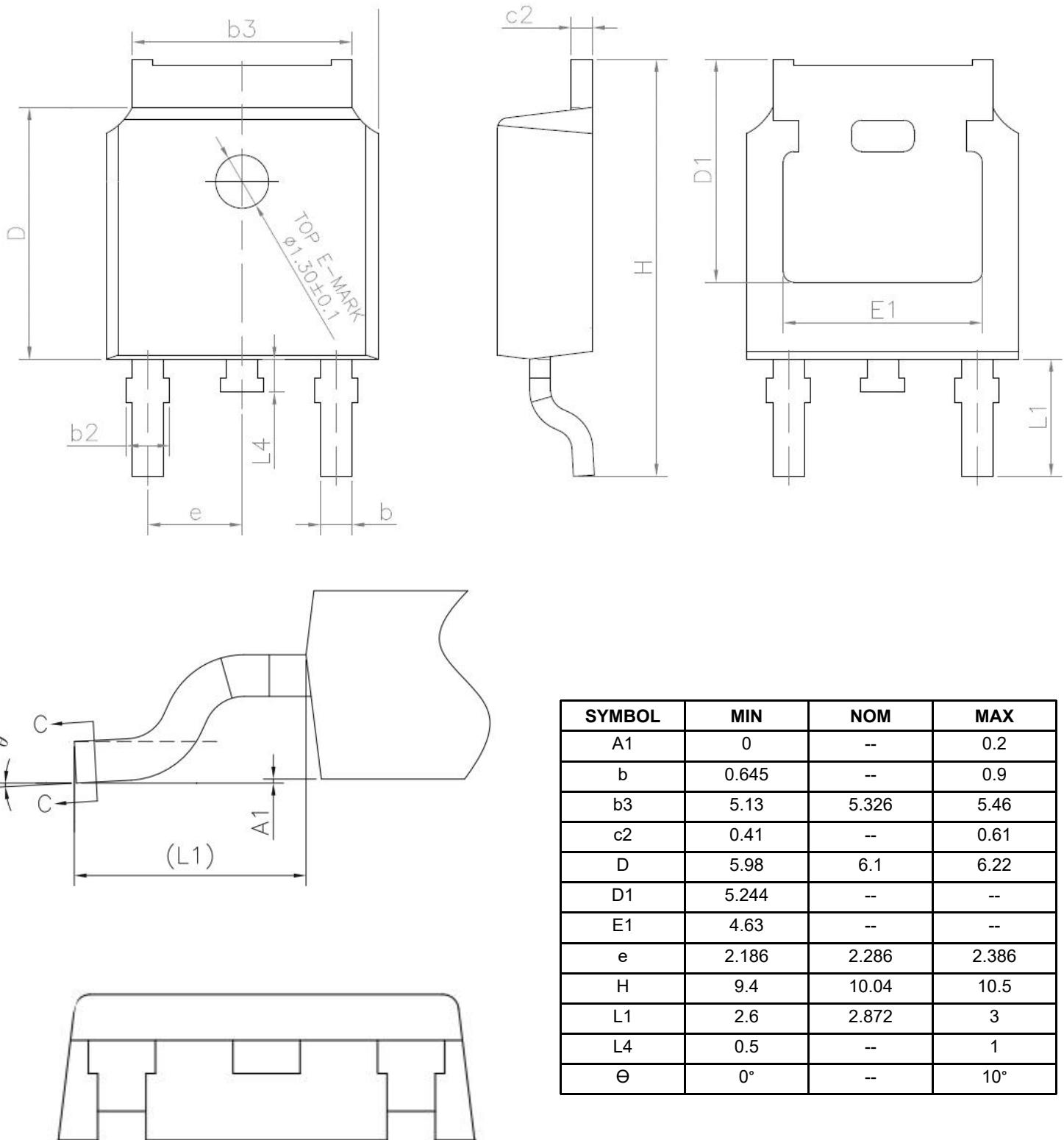


Outlines TO-263 Package

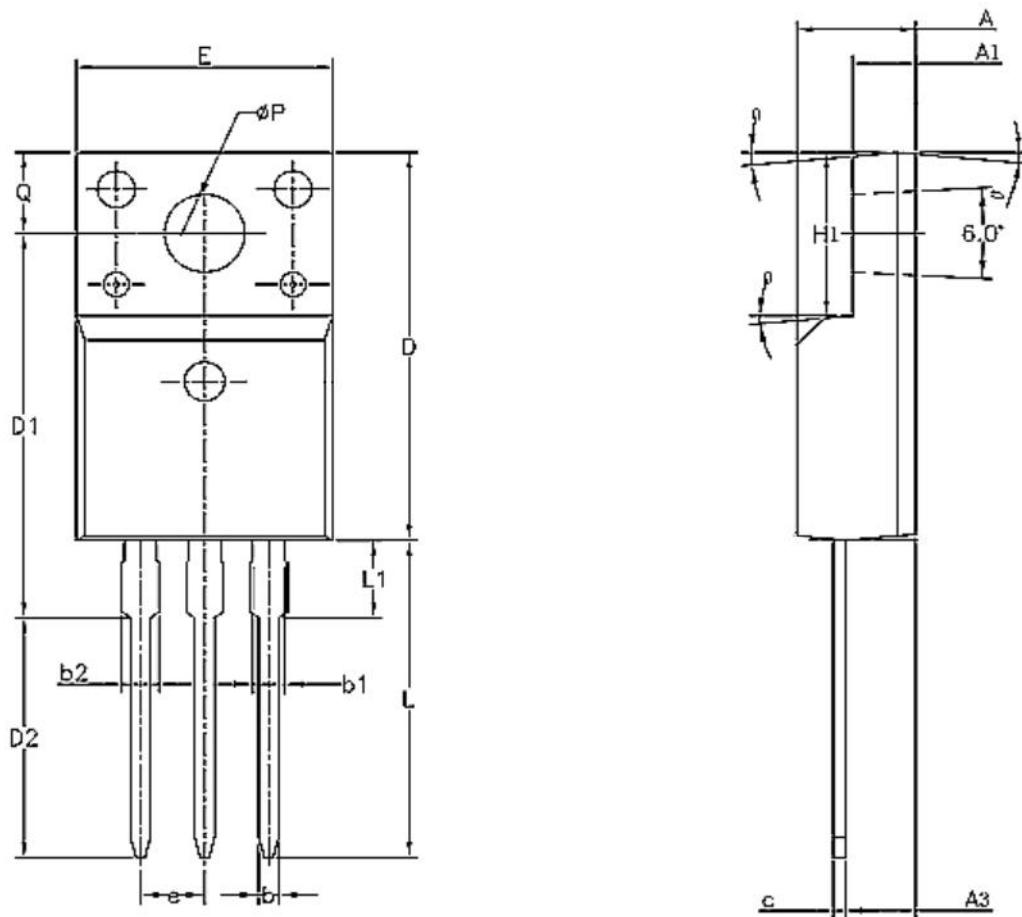


SYMBOL	MIN	NOM	MAX
A	4.40	4.50	4.60
A1	0	0.10	0.25
A2	2.20	2.40	2.60
b	0.76	--	0.89
B1	0.75	0.80	0.85
B2	1.23	--	1.37
b3	1.22	1.27	1.32
c	0.47	--	0.60
c1	0.46	0.51	0.56
c2	1.25	1.30	1.35
D	9.10	9.20	9.30
D1	8.00	--	--
E	9.80	9.90	10.00
E1	7.80	--	--
e	2.54 BSC		
H	14.90	15.30	15.70
L	2.00	2.30	2.60
L1	1.17	1.27	1.40
L2	--	--	1.75
L3	0.25 BSC		
L4	4.60 REF		
Θ	0°	--	8°
Θ1	1°	3°	5°

Outlines TO-252 Package



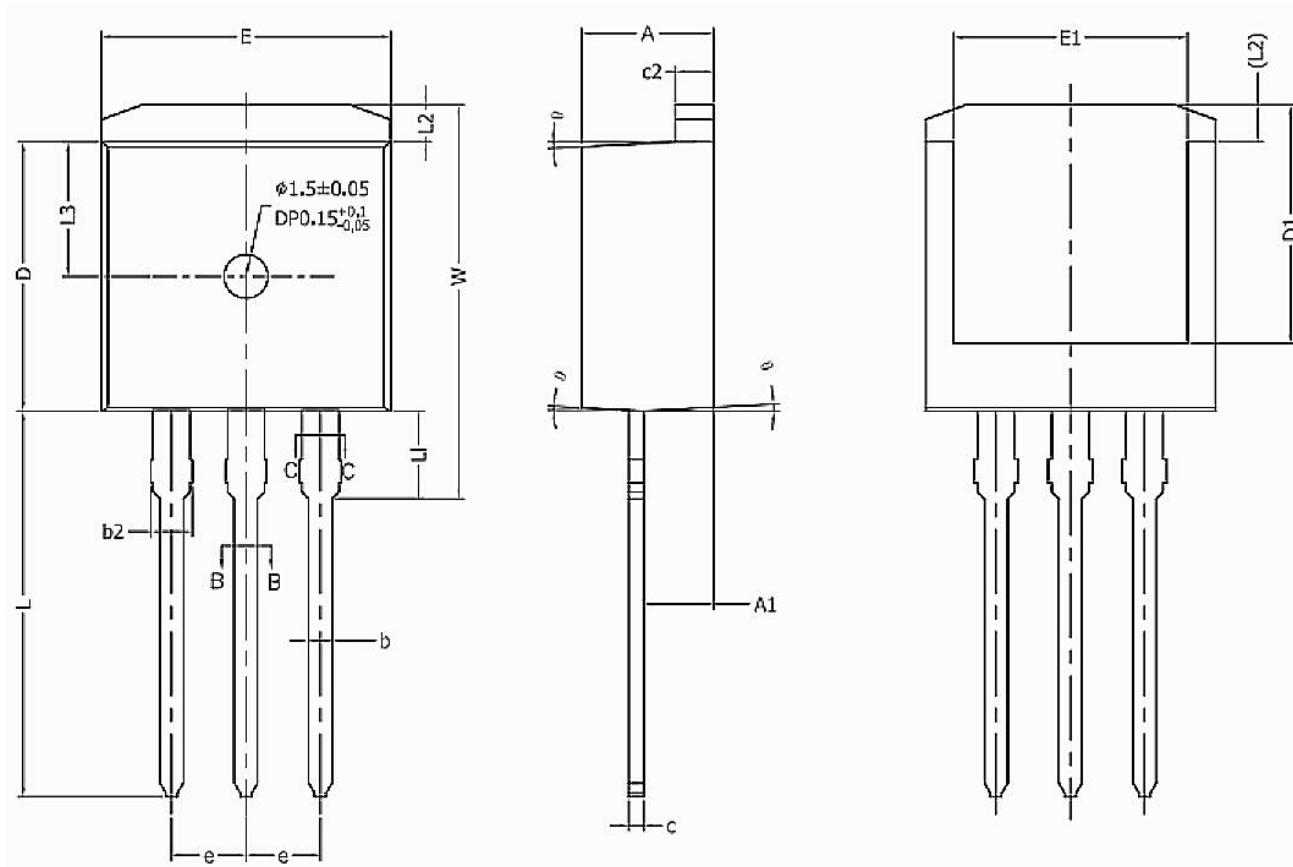
Outlines TO-220F Package



SYMBOL	MIN	NOM	MAX
A	4.5	4.7	4.9
A1	2.34	2.54	2.74
A3	2.56	2.76	2.96
b	0.7	---	0.95
b1	1.18	---	1.43
b2	---	---	1.55
c	0.4	0.5	0.65
D	15.57	15.87	16.17

SYMBOL	MIN	NOM	MAX
D1	15.35	15.675	15.95
D2	9.6	9.875	10.15
E	9.96	10.16	10.36
e	2.54 BSC		
H1	6.48	6.68	6.88
L	12.68	12.98	13.28
L1	---	---	3.5

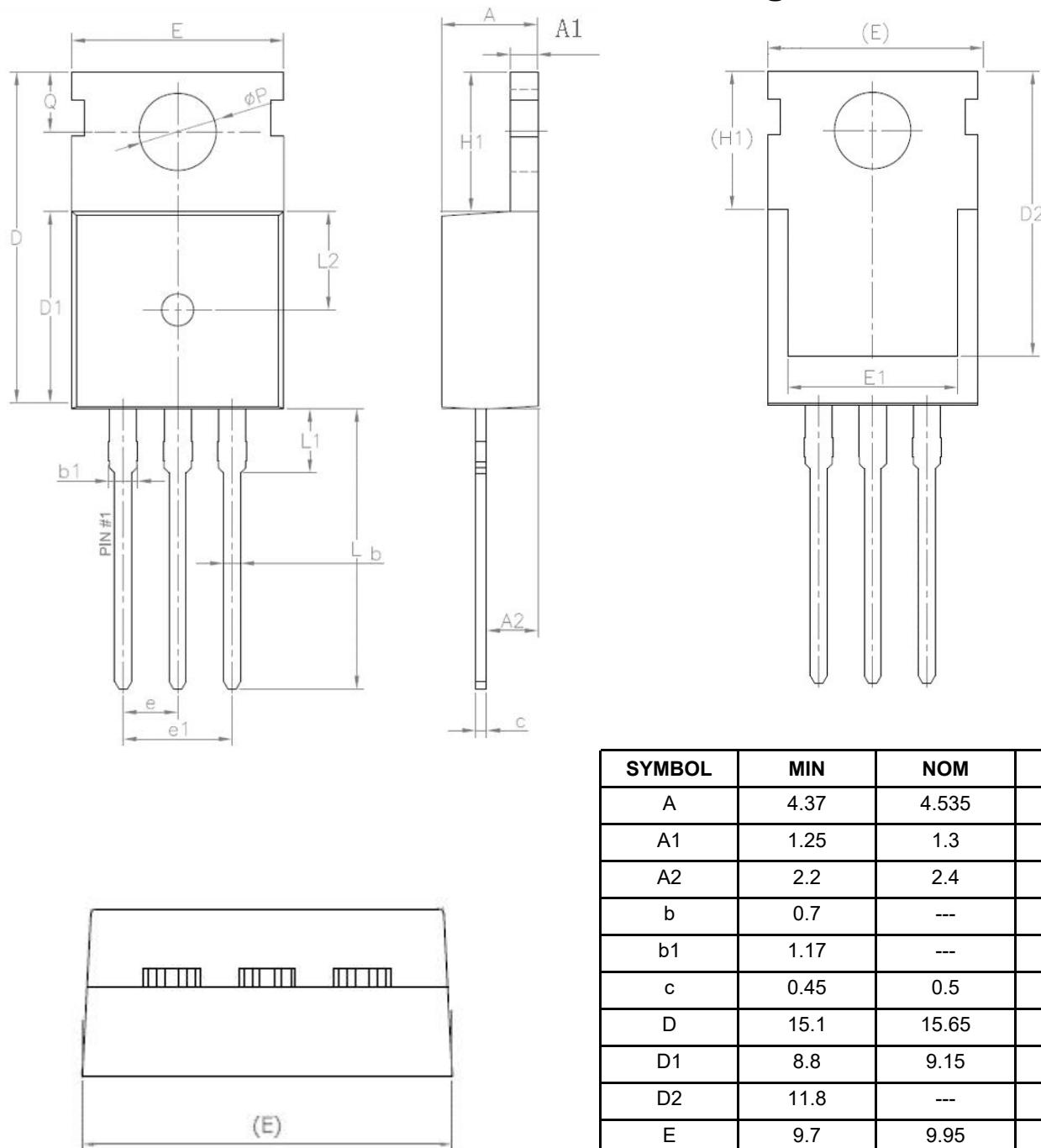
Outlines TO-262 Package



Unit:mm			
Symbol	Min.	Nom	Max.
A	4.40	4.50	4.60
A1	2.20	2.40	2.60
b	0.76	---	0.89
b1	0.75	0.80	0.85
b2	1.23	---	1.37
b3	1.22	1.27	1.32
c	0.47	---	0.60
c1	0.46	0.51	0.56
c2	1.25	1.30	1.35
D	9.10	9.20	9.30

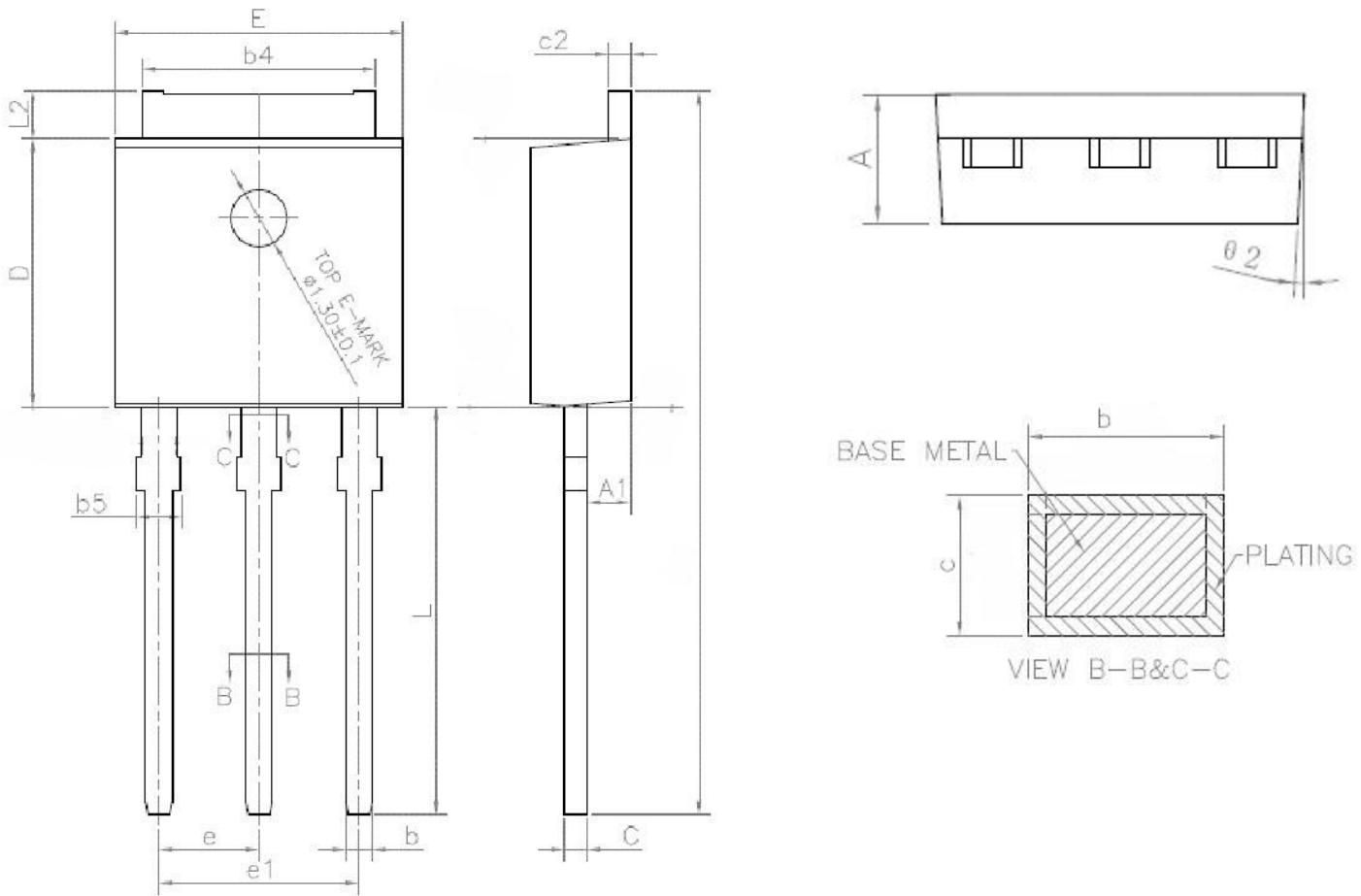
Unit:mm			
Symbol	Min.	Nom	Max.
D1	8.00	---	---
E	9.80	9.90	10.00
E1	7.80	---	---
e	2.54 BSC		
L	12.90	13.20	13.50
L1	2.80	3.00	3.20
L2	1.17	1.27	1.40
L3	4.60 REF		
W	13.25	---	14.00
θ	1°	3°	5°

Outlines TO-220 Package



SYMBOL	MIN	NOM	MAX
A	4.37	4.535	4.7
A1	1.25	1.3	1.4
A2	2.2	2.4	2.6
b	0.7	---	0.95
b1	1.17	---	1.47
c	0.45	0.5	0.6
D	15.1	15.65	16.1
D1	8.8	9.15	9.4
D2	11.8	---	---
E	9.7	9.95	10.3
E1	7	---	---
e	2.54 BSC		
e1	5.08 BSC		
H1	6.25	6.5	6.85
L	12.75	13.29	13.8
L1	---	---	3.5
ΦP	3.4	3.67	3.8
Q	2.6	---	3

Outlines TO-251 Package



SYMBOL	MIN	NOM	MAX
A	2.20	2.30	2.38
A1	0.90	1.04	1.17
b	0.56	--	0.90
b4	5.20	5.33	5.46
b5	--	--	1.05
c	0.43	--	0.61
c2	0.43	--	0.61
D	5.98	6.10	6.22
D1	5.2	--	--
E	6.40	6.60	6.73
E1	4.60	--	--
e	2.24	2.29	2.34
e1	4.47	4.57	4.67
H	16.18	16.50	16.82
L	9	9.35	9.65
L2	0.88	1.05	1.28

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.